

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6033863

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JUNICHI HIROTSU	03/10/2020
DAIKI ITO	03/10/2020
RECEIVING PARTY DATA	
Name:	WINBOND ELECTRONICS CORP.
Street Address:	NO. 8 KEYA 1ST RD., DAYA DISTRICT
Internal Address:	CENTRAL TAIWAN SCIENCE PARK
City:	TAICHUNG CITY
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16830983
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	0941-4335PUS1
NAME OF SUBMITTER:	LYNN LAM
SIGNATURE:	/lynn lam/
DATE SIGNED:	03/26/2020
Total Attachments: 1	
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ASSIGNMENT

WHEREAS, Junichi HIROTSU and Daiki ITO
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements
as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR DEVICE

Filed: _____ Serial No. _____

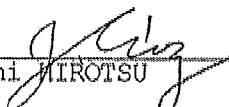
Executed on: _____

WHEREAS, Winbond Electronics Corp. of No. 8 Keya 1st Rd.,
Daya District, Central Taiwan Science Park, Taichung City,
Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring
ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent
which may be granted on the same;

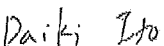
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for
good and valuable consideration, receipt of which is hereby acknowledged by Assignor,
Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign
and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their
rights, title and interest in and to the said invention and application and all future
improvements thereon, and in and to any Letters Patent which may hereafter be granted on the
same in the United States, the said interest to be held and enjoyed by said Assignee as fully
and exclusively as it would have been held and enjoyed by said Assignor had this Assignment
and transfer not been made, to the full end and term of any Letters Patent which may be
granted thereon, or of any division, renewal, continuation in whole or in part, substitution,
conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said
Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said
application and/or applications, execute, verify, acknowledge and deliver all such further
papers, including applications for Letters Patent and for the reissue thereof, and instruments
of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may
request, to obtain or maintain Letters Patent for said invention and improvement, and to vest
title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the
date(s) indicated.


Junichi HIROTSU

March 10, 2020
Date


Daiki ITO

March 10, 2020
Date